

RELIABILITY REPORT
FOR
MAX4781ExE+
PLASTIC ENCAPSULATED DEVICES

July 28, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Conclusion

The MAX4781ExE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
.....Attachments	

I. Device Description

A. General

The MAX4781/MAX4782/MAX4783 are high-speed, low-voltage, low on-resistance, CMOS analog multiplexers/ switches configured as an 8-channel multiplexer (MAX4781), two 4-channel multiplexers (MAX4782), and three single-pole/double-throw (SPDT) switches (MAX4783). These devices operate with a +1.6V to +3.6V single supply. When powered from a +3V supply, MAX4781/ MAX4782/MAX4783 feature a 0.7 Ω on-resistance (RON), with 0.3 Ω RON matching between channels, and 0.1 Ω RON flatness. These devices handle rail-to-rail analog signals while consuming less than 3 μ W of quiescent power. They are available in space-saving 16- pin thin QFN (3mm x 3mm) and TSSOP packages.

II. Manufacturing Information

A. Description/Function:	High-Speed, Low-Voltage, 0.7 CMOS Analog Switches/Multiplexers	
B. Process:	TS35	
C. Number of Device Transistors:		
D. Fabrication Location:	Taiwan	
E. Assembly Location:	Philippines, Thailand	Philippines, China, Malaysia, Thailand
F. Date of Initial Production:	July 26, 2002	

III. Packaging Information

A. Package Type:	16-pin TSSOP	16-pin TQFN 3x3 mm
B. Lead Frame:	Copper	Copper
C. Lead Finish:	100% matte Tin	100% matte Tin
D. Die Attach:	Conductive Epoxy	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0295	#05-9000-1140
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1	Level 1
J. Single Layer Theta Ja:	106°C/W	64°C/W
K. Single Layer Theta Jc:	27°C/W	6.9°C/W
L. Multi Layer Theta Ja:	90°C/W	48°C/W
M. Multi Layer Theta Jc:	27°C/W	6.9°C/W

IV. Die Information

A. Dimensions:	60 X 58 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35µm
F. Minimum Metal Spacing:	0.35µm
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 42 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 25.6 \times 10^{-9}$$

$$\lambda = 25.6 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the TS352P3M Process results in a FIT Rate of 0.43 @ 25C and 7.50 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AH82 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4781EUE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	42	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data